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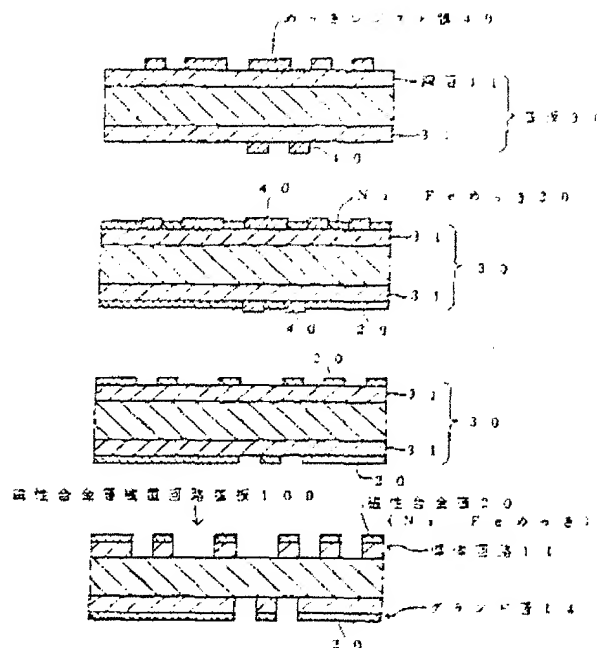
APPLICATION DATE : 04-10-89
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APPLICANT : IBIDEN CO LTD;

INVENTOR : OTSUKI KAZUYUKI;

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TITLE : MAGNETIC ALLOY LAYER COATED
CIRCUIT BOARD



ABSTRACT : PURPOSE: To reduce influence of magnetic noises remarkably and to enable magnetic shield at a unit of semiconductor element by covering a conductor pattern with an alloy layer which is Ni and Fe based highly permeable magnetic body.

CONSTITUTION: A plating resist film 40 is formed on a glass triazine substrate 30 where to a copper foil 31 is applied. Ni/Fe plating 20 is applied to a surface of the copper foil 31 by electrolytic method. Then, after the plating resist film 40 is peeled off, a part of the copper foil 31 which is exposed by alkaline solution immersion is etched. A magnetic alloy layer coated circuit board 100 having a conductor circuit 11 covered with the magnetic alloy layer 20 of Ni/Fe plating 20 or a ground layer 14 is formed in this way.

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